

**SEMICONDUCTOR PACKAGE****ABSTRACT OF THE DISCLOSURE**

A semiconductor package with a flash-proof device is proposed, in which at  
5 least one chip and at least one passive device mounted on a substrate are covered by  
a flash-proof device dimensionally designed for positioning the substrate in a  
conventional mold and preventing a molding resin from flashing on the substrate in a  
molding process, and thus quality of the fabricated package can be assured. Due to  
no need of a specifically designed mold, fabrication costs are reduced. Furthermore,  
10 the flash-proof device has its top side exposed to outside of an encapsulant formed in  
the molding process, thereby allowing heat dissipating efficiency to be improved.  
Moreover, the flash-proof device provides shielding for the chip and the passive  
device received therein, so that external electromagnetic interference with  
performance of the semiconductor package can be reduced.

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